

## ABSTRACT

The present invention provides a thermally conductive pressure-sensitive adhesive composition comprising an acrylic (or methacrylic) ester copolymer obtained by polymerizing a monomer mixture comprising an acrylic (or methacrylic) ester monomer capable of forming a homopolymer having a glass transition temperature of  $-20^{\circ}\text{C}$  or lower, a monomer having an organic acid group, and a monomer copolymerizable with these monomers in the presence of a copolymer comprising acrylic (or methacrylic) ester monomer units capable of forming a homopolymer having a glass transition temperature of  $-20^{\circ}\text{C}$  or lower, monomer units having an organic acid group, monomer units having a functional group other than any organic acid group and monomer units copolymerizable with these monomer units, and a metal hydroxide, wherein the acrylic (or methacrylic) ester copolymer is foamed, the composition being excellent in balance between hardness and pressure-sensitive adhesive property, having excellent shape-conformability and other performances, and being able to be made into a sheet easily be molded and the obtained sheet can easily be peeled from an adherend to which the sheet adheres easily after the sheet is used; a thermally conductive sheet-form molded foam comprising this composition; and a process for producing the same.